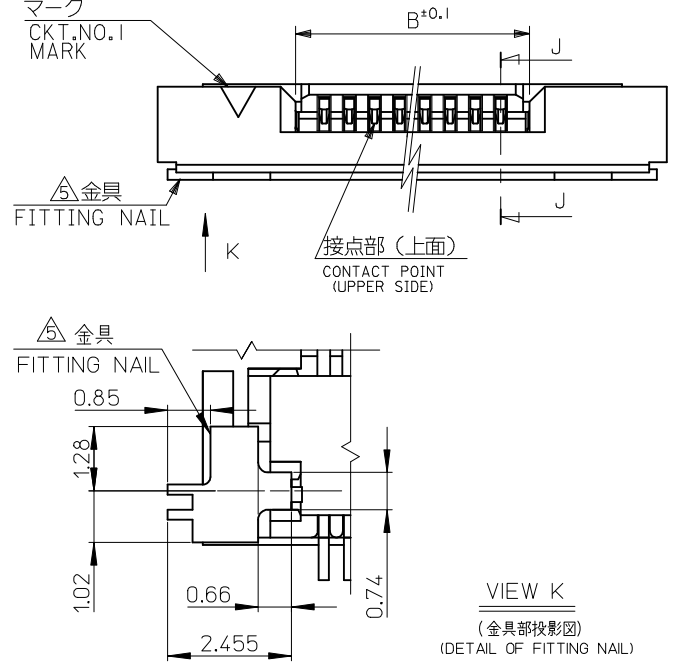
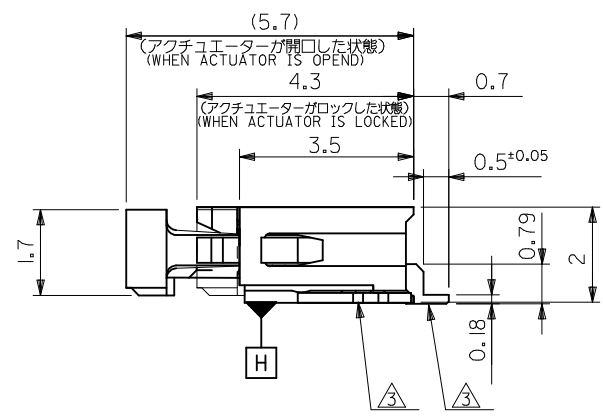
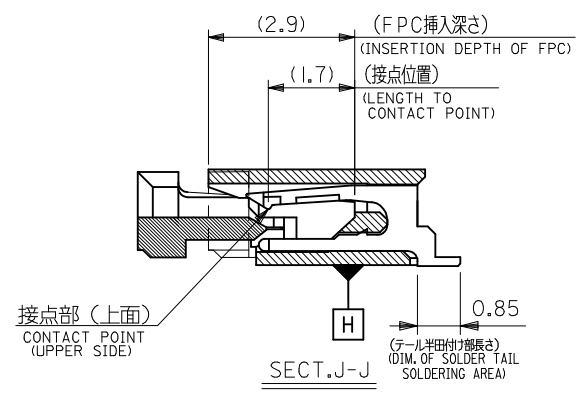
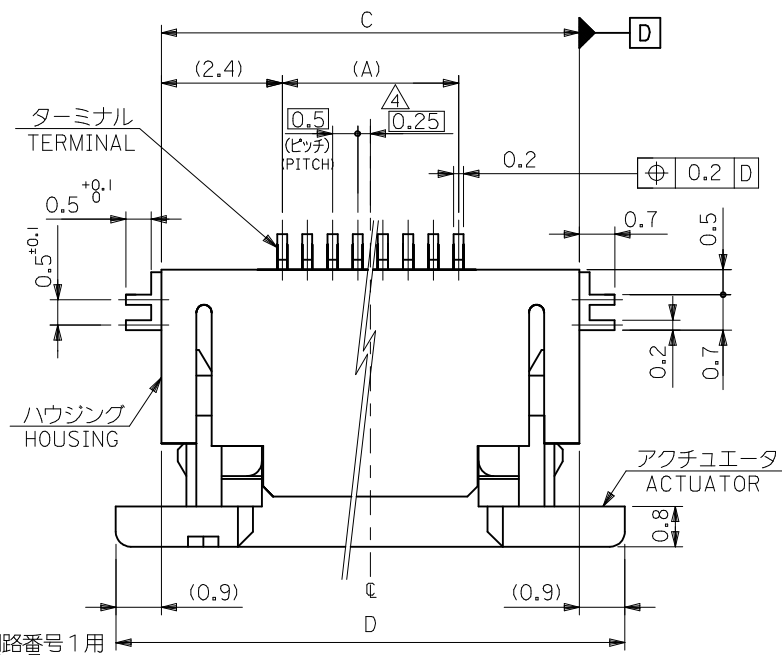




16.1	14.3	10.65	9.5	52745-2090	20
15.6	13.8	10.15	9	52745-1990	19
15.1	13.3	9.65	8.5	52745-1890	18
14.1	12.3	8.65	7.5	52745-1690	16
13.6	11.8	8.15	7	52745-1590	15
12.6	10.8	7.15	6	52745-1390	13
11.6	9.8	6.15	5	52745-1190	11
11.1	9.3	5.65	4.5	52745-1090	10
10.6	8.8	5.15	4	52745-0990	9
10.1	8.3	4.65	3.5	52745-0890	8
9.6	7.8	4.15	3	52745-0790	7
9.1	7.3	3.65	2.5	52745-0690	6
8.1	6.3	2.65	1.5	52745-0490	4
D	C	B	(A)	EMBOSSED PACKAGE ORDER No. オーダー番号	極数 CKT.

CONNECTOR SERIES NO. : 52745-**17

REVISED EC NO: J2015-0016 DRWN: THIRAYAMA 2014/07/09 CHKD: YKOBAYASHI 2014/07/09 APPR: YNOGAWA 2014/07/17	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER ±0.2		DRAWN BY DATE SAI HARA 1994/03/24		TITLE 0.5 FPC CONN. ZIF FOR SMT R/A (UPPER CONTACT) TIN-LEAD PLATING molex			
		10 OVER 30 UNDER ±0.25		CHECKED BY DATE SKUNISHI 2000/06/30					
		30 OVER ±0.3		APPROVED BY DATE KMORIKAWA 2010/07/16					
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
	REV	J	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		SEE CHART THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
					SD-52745-054 1 OF 2				

注記NOTES

1.使用材料

MATERIAL

ハウジング：46ナイロン、ガラス充填、UL94V-0、白
HOUSING:PA46, GLASS FILLED, UL94V-0, WHITE
アクチュエータ：ポリフェニレンサルファイド (PPS)、ガラス充填、UL94V-0、黒
ACTUATOR: POLYPHENYLENE SULFIDE, GLASS FILLED, UL94V-0, BLACK
ターミナル：リン青銅、銅下地半田めっき (t=0.2)
TERMINAL: PHOSPHOR BRONZE, TIN-LEAD OVER COPPER PLATING
金具：リン青銅、銅下地半田めっき (t=0.2)
FITTING NAIL: PHOSPHOR BRONZE, TIN-LEAD OVER COPPER PLATING

2.エンボステープ梱包時は、アクチュエータがロックした状態になります。

IN THE PACKAGE, ACTUATOR OF PART NO.52745-**17 SHOULD BE LOCKED.

△3 ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面Hに対して上方向に0.1MAXIMUM、下方向0.15MAXIMUMとする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM DATUM-H.

UPPER DIRECTON:0.1MAXIMUM

LOWER DIRECTION:0.15 MAXIMUM

△4 偶数極に適用

APPLY FOR EVEN CIRCUIT.

△5 ハ' ターン剥離止め金具

FITTING NAIL FOR PREVENTION OF PEELING OF P.W.B. PATTERN.

△6 R0.3は、FPCの胴体部にかからないこと
R0.3 MUST NOT BE OVERLAPED TO PATTERN OF FPC.

FPCについて：

打抜き方向は導体側から補強板を推奨致します。

補強フィルム材質はポリイミドを推奨致します。

接着剤は熱硬化接着剤を推奨致します。

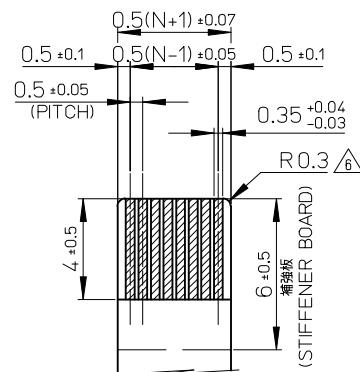
ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.

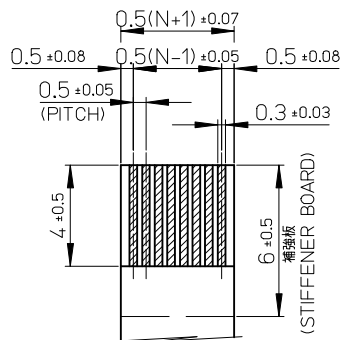
RECOMMENDED MATERIAL :

STIFFENER FILM : POLYIMIDE

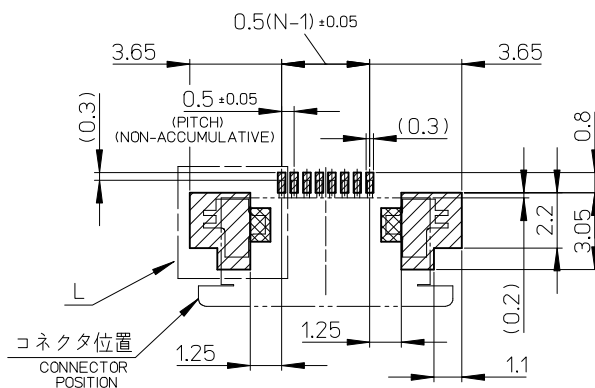
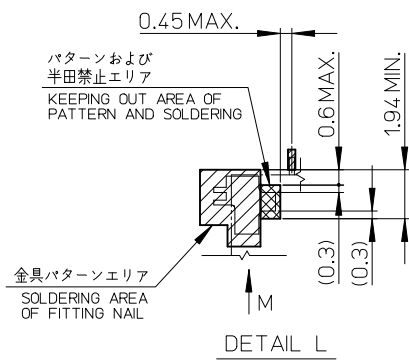
BONDING AGENT : THERMOSETTING BONDING AGENT



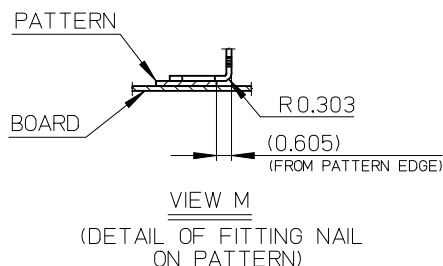
適合金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD
PLATING RECOMMENDED DIMENSION
仕上がり厚さ：0.3±0.03
THICKNESS: 0.3+0.03/-0.03



適合金めっきFFC推奨寸法
APPLICABLE FFC OF GOLD
PLATING RECOMMENDED DIMENSION
仕上がり厚さ：0.3±0.03
THICKNESS: 0.3+0.03/-0.03



参考基板レイアウト
(マウント面)
RECOMMENDED P.C. BOARD
PATTERN DIMENSION (REF.)
(MOUNTING SIDE)



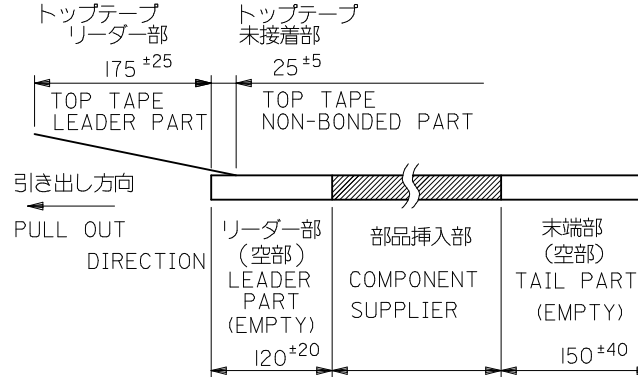
REVISED	EC NO.: J2015-0016 DRAWN: THIRAYAMA 2014/07/09 CHKD: YKOBAYASHI 022014/07/10 APPR: YNOGAWA 2014/07/17	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			10 UNDER	± ---	DRAWN BY SAIHARA	DATE 1994/03/24	TITLE 0.5 FPC CONN. ZIF FOR SMT R/A (UPPER CONTACT) TIN-LEAD PLATING molex				
			10 OVER 30 UNDER	± ---	CHECKED BY SKUNISHI	DATE 2000/06/30					
			30 OVER	± ---	APPROVED BY KMORIKAWA	DATE 2010/07/16					
			ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1 OF 2		SD-52745-054		2 OF 2		
REV			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

注記 NOTES

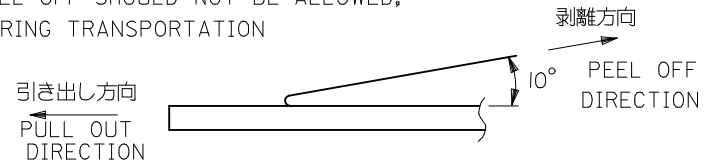
1. 製品番号 52745-**17 の梱包状態はアクチュエータがロックした状態とする。
詳細寸法については図面 SD-52745-054 を参照下さい。
IN THE PACKAGE,ACTUATOR OF PART NO.52745-**17 SHOULD BE LOCKED
RE DETAILED DIMENSIONS,SEE SD-52745-054

2. 梱包数量：1000個／リール
NUMBER OF CONNECTORS:1000PCS/REEL

3. リードテープ長さ LEAD TAPE LENGTH

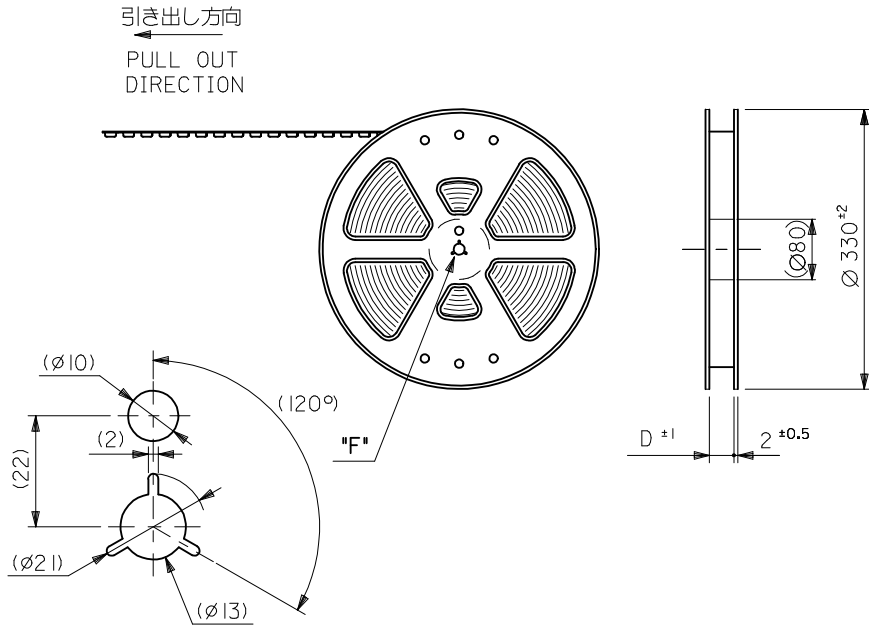


4. トップテープの剥離強度：(剥離方向は下図参照)
0.1N～0.7N (10.2gf～71.4gf) 尚、本規格値は、出荷時に適用。
(但し、輸送時に剥離が発生しない事。)
PEELING OFF FORCE OF TOP TAPE
0.1N～0.7N(10.2gf～71.4gf)(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
PEEL OFF SHOULD NOT BE ALLOWED,
DURING TRANSPORTATION



REVISED EC NO: J2015-0016 DRWN: THIRAYAMA 2014/07/10 CHKD: YKOBAYASHI 2014/07/10 APPR: YNOGAWA 2014/07/17	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER ± ---		DRAWN BY DATE MTAKAHASHI 04 2013/07/30		TITLE 0.5 FPC CONN ZIF SMT RA UPPER CONTACT EMBSTP PKG (1/3)			
		10 OVER 30 UNDER ± ---		CHECKED BY DATE KTAKAHASHI 2013/07/30					
		30 OVER ± ---		APPROVED BY DATE YNOGAWA 2013/11/07					
		ANGULAR ± --- °		MATERIAL NO.		DOCUMENT NO. molex SD-52745-057			
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SHEET NO. 1 OF 3				
	B	REV			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

DETAIL "F"



5. 材料
キャリアテープ：ポリプロピレン (PP)
トップテープ：PET, PE, PEF
リール：ポリスチレン (PS) <リサイクル材を含む>

MATERIAL CARRIER TAPE:POLYPROPYLENE
TOP TAPE:PET,PE,PEF
REEL:POLYSTYREN(PS)
<RECYCLE MATERIAL CONTAINED>

10 9 8 7 6 5 4 3 2 1

F

E

D

C

B

A

F

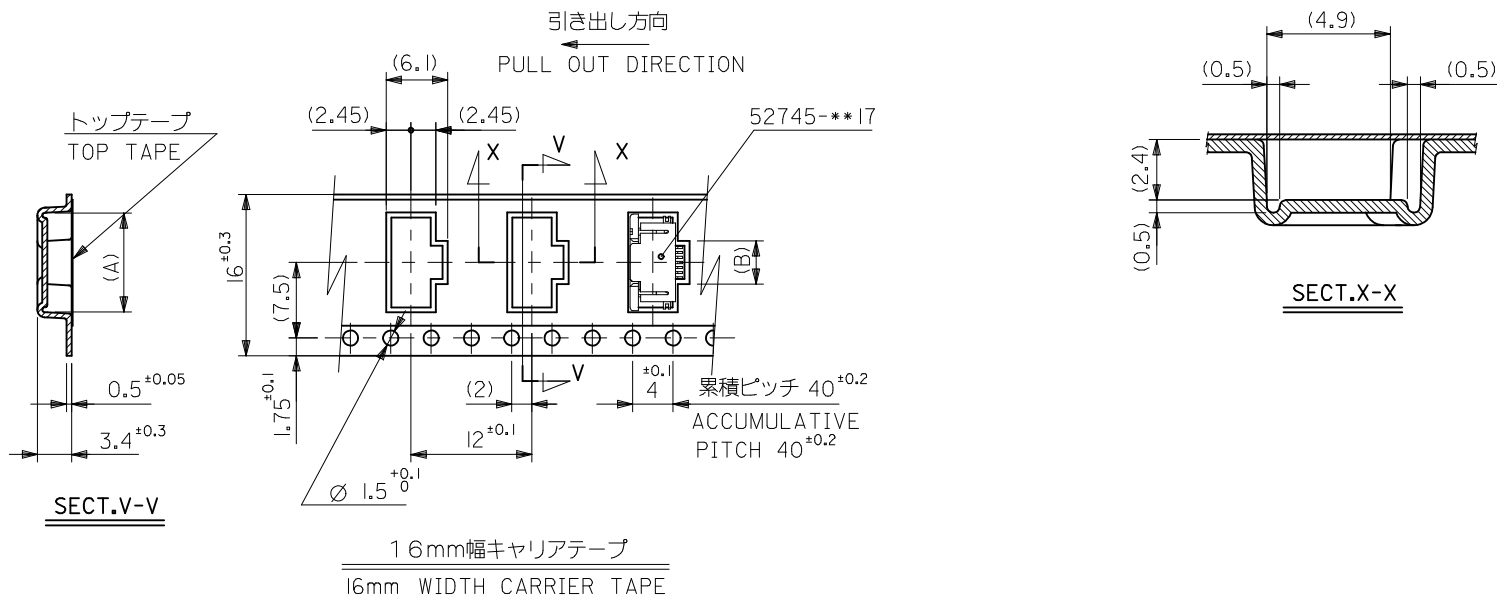
E

D

C

B

A



16	17.5	2.8	8.4	52745-0490	4
キャリアテープ幅 CARRIER TAPE WIDTH	D	(B)	(A)	ENG. NO.	極数 CIRCUIT

REVISED EC NO: J2015-0016 DRWN: THIRAYAMA 2014/07/10 CHKD: YKOBAYASHI 2014/07/10 APPR: YNOGAWA 2014/07/17	DESCRIPTION		GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
			10 UNDER	± --	DRAWN BY	DATE	TITLE 0.5 FPC CONN ZIF SMT RA UPPER CONTACT EMBSTP PKG (3/3)			
			10 OVER 30 UNDER	± ---	CHECKED BY	DATE				
			30 OVER	± ---	APPROVED BY	DATE	DOCUMENT NO. SD-52745-057			
			ANGULAR	± --- °	MATERIAL NO.	2013/11/07				
REV		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

9 8 7 6 5 4 3 2